

Final Product Change Notification

202201018F01: ASEK WT/Grinding/Sawing 2nd Source to ATBK - NX20P3481 and NX20P3483

Note: This notice is NXP Company Proprietary.

Issue Date: Mar 07, 2022 Effective date: Jun 10, 2022

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Management summary

Adding ATBK as a 2nd source of current ASEK WT & BE2 activities

Change Category

[]Wafer Fab Process	[]Assembly Process	[]Product Marking	[]Test Process	[]Design
[]Wafer Fab Materials	[]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[]Wafer Fab Location	[]Assembly Location	[X]Packing/Shipping/Labeling	[X]Test Location	[]Electrical spec./Test coverage
[]Firmware	[X]Other: Grinding/Sawing/Pa	acking		

PCN Overview

Description

Expanding the current flow which is currently limited to an ASE Assembly and WT (turnkey) to allow for ATBK WT and BE2.

The flow allows for manufacturing flexibility and helps ensure customer supply.

WT and BE2(back half of the Assembly process - grinding/sawing/marking and Packing) will be enabled in ATBK.

Reason

The flow allows for manufacturing flexibility and helps ensure customer supply.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Jun 10, 2022

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

WT and BE2 Expansion. No Depletion of Inventory required.

Packing Method and 12NC ordering number no change.

Additional information

Self qualification: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Apr 06, 2022.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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Changed Orderable Part#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	New Orderable Part#	12NC New	Product Type New	Product Description New	Product Line	Notes
NX20P3481UKAZ	935356755012	NX20P3481UK	20V Bi-direction Type-C Load Switch			RFS	No					BLC4	
NX20P3483UKAZ	935357666012	NX20P3483UK	20V Bidirection Type-C Load Switch			RFS	No					BLC4	